

NHPM120, NRVHPM120

Surface Mount Ultra Fast Power Rectifier

POWERMITE® Power Surface Mount Package

This ultrafast POWERMITE provides soft recovery fast switching performance in a compact thermally efficient package. The advanced packaging techniques provide for a very efficient micro-miniature space-saving surface mount rectifier. With its unique heatsink design, the POWERMITE offers thermal performance similar to the SMA while being 50% smaller in footprint area.

Features

- Fast Soft Switching for Reduced EMI and Higher Efficiency
- Low Profile – Maximum Height of 1.1 mm
- Small Footprint – Footprint Area of 8.45 mm²
- Supplied in 12 mm Tape and Reel
- Low Thermal Resistance with Direct Thermal Path of Die on Exposed Cathode Heat Sink
- NRV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Mechanical Characteristics:

- POWERMITE is JEDEC Registered as D0-216AA
- Case: Molded Epoxy
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 16.3 mg (Approximately)
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Maximum for 10 Seconds
- MSL 1

Applications

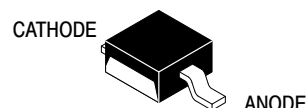
- Automotive LED Lighting
- Engine Control
- Freewheeling Diode Where Space is at a Premium
- Flat Panel Display



ON Semiconductor®

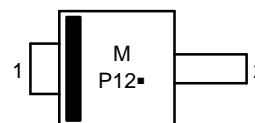
<http://onsemi.com>

ULTRAFAST RECTIFIER 1.0 AMPERE, 200 VOLTS



POWERMITE
CASE 457

MARKING DIAGRAM



M = Date Code
P12 = Device Code
■ = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping†
NHPM120T3G	POWERMITE (Pb-Free)	12000 / Tape & Reel
NRVHPM120T3G	POWERMITE (Pb-Free)	12000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NHPM120, NRVHPM120

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	200	V
Average Rectified Forward Current ($T_L = 165^\circ\text{C}$)	I_O	1.0	A
Peak Repetitive Forward Current (Rated V_R , Square Wave, 20 kHz) $T_L = 165^\circ\text{C}$	I_{FRM}	2.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I_{FSM}	30	A
Storage and Operating Junction Temperature Range (Note 1)	T_{stg}, T_J	-65 to +175	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- The heat generated must be less than the thermal conductivity from Junction-to-Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Note 2)	Ψ_{JCL}	12	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	75	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient (Note 3)	$R_{\theta JA}$	260	$^\circ\text{C/W}$

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 4) ($I_F = 1.0 \text{ A}, T_J = 25^\circ\text{C}$) ($I_F = 2.0 \text{ A}, T_J = 25^\circ\text{C}$) ($I_F = 1.0 \text{ A}, T_J = 125^\circ\text{C}$) ($I_F = 2.0 \text{ A}, T_J = 125^\circ\text{C}$)	V_F	1.0 1.1 0.85 0.95	V
Maximum Instantaneous Reverse Current (Note 4) (Rated dc Voltage, $T_J = 25^\circ\text{C}$) (Rated dc Voltage, $T_J = 125^\circ\text{C}$)	I_R	0.5 25	μA
Reverse Recovery Time $I_F = 1.0 \text{ A}, V_R = 30 \text{ V}, dI/dt = 50 \text{ A}/\mu\text{s}, T_J = 25^\circ\text{C}$	t_{rr}	25	ns
Reverse Recovery Time $I_F = 1.0 \text{ A}, V_R = 30 \text{ V}, dI/dt = 50 \text{ A}/\mu\text{s}, T_J = 50^\circ\text{C}$	t_{rr}	50	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- Mounted with 700 mm² copper pad size (Approximately 1 in²) 1 oz FR4 Board.
- Mounted with pad size approximately 20 mm² copper, 1 oz FR4 Board.
- Pulse Test: Pulse Width $\leq 380 \mu\text{s}$, Duty Cycle $\leq 2.0\%$.

NHPM120, NRVHPM120

TYPICAL CHARACTERISTICS

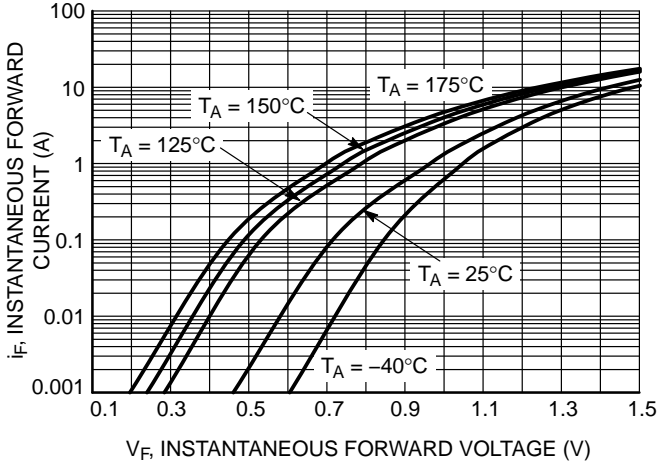


Figure 1. Typical Instantaneous Forward Characteristics

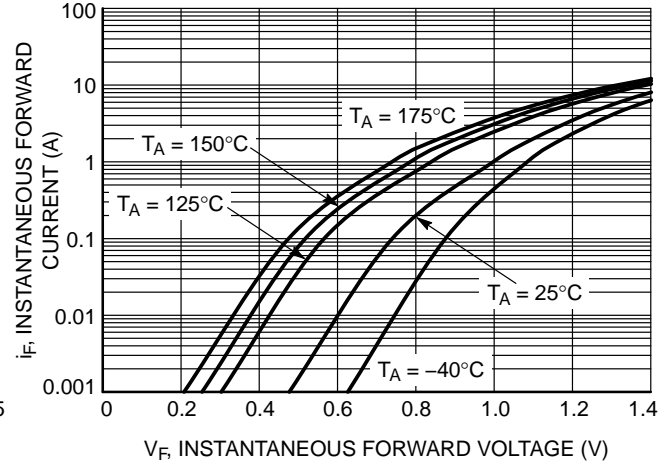


Figure 2. Maximum Instantaneous Forward Characteristics

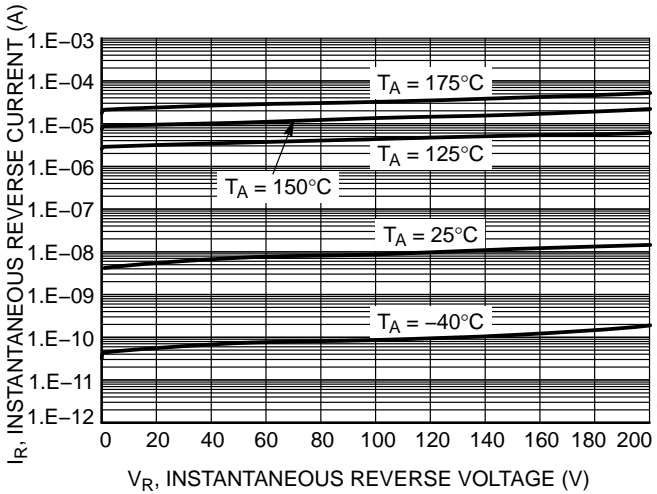


Figure 3. Typical Reverse Characteristics

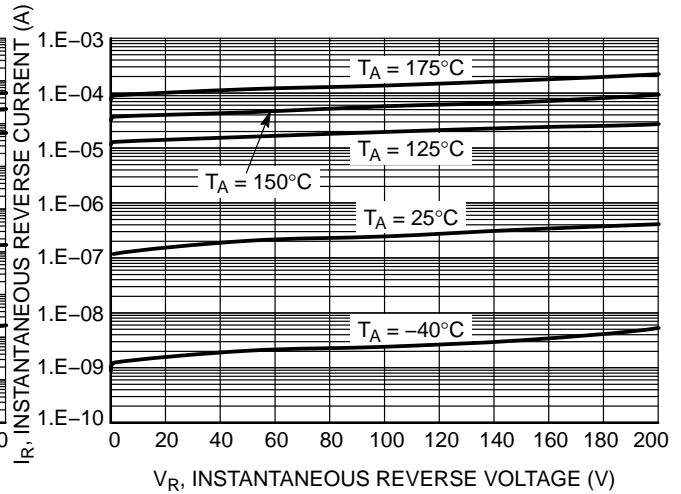


Figure 4. Maximum Reverse Characteristics

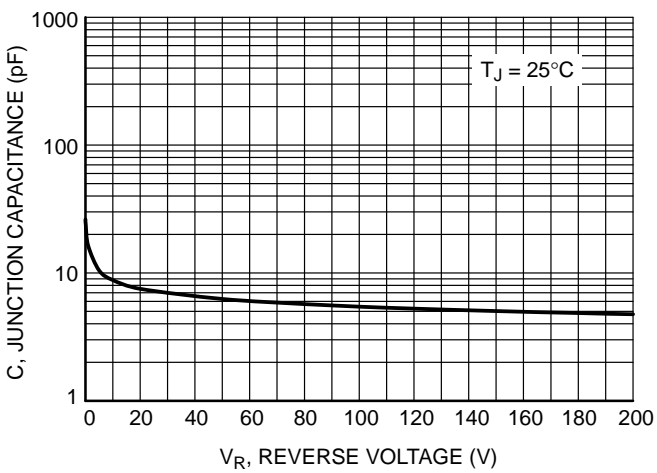


Figure 5. Typical Junction Capacitance

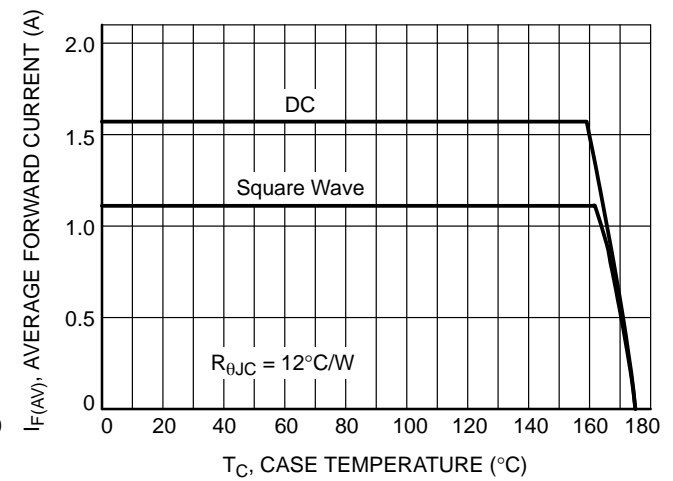


Figure 6. Current Derating

NHPM120, NRVHPM120

TYPICAL CHARACTERISTICS

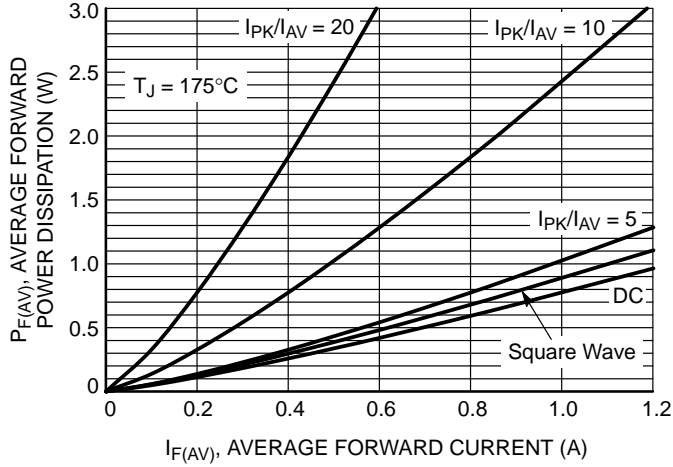


Figure 7. Forward Power Dissipation

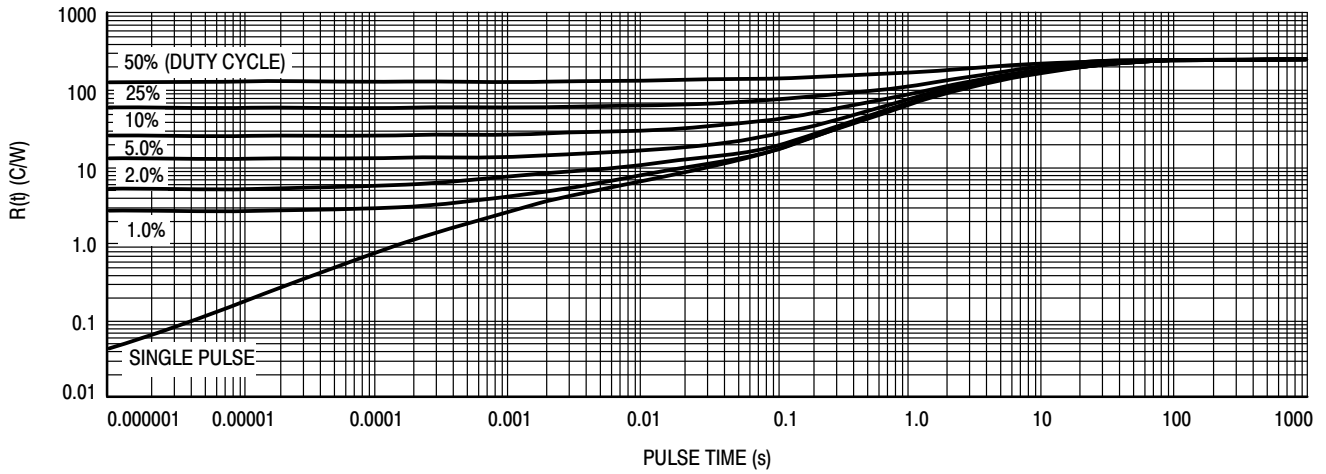


Figure 8. Thermal Response, Junction-to-Ambient (20 mm^2 pad)

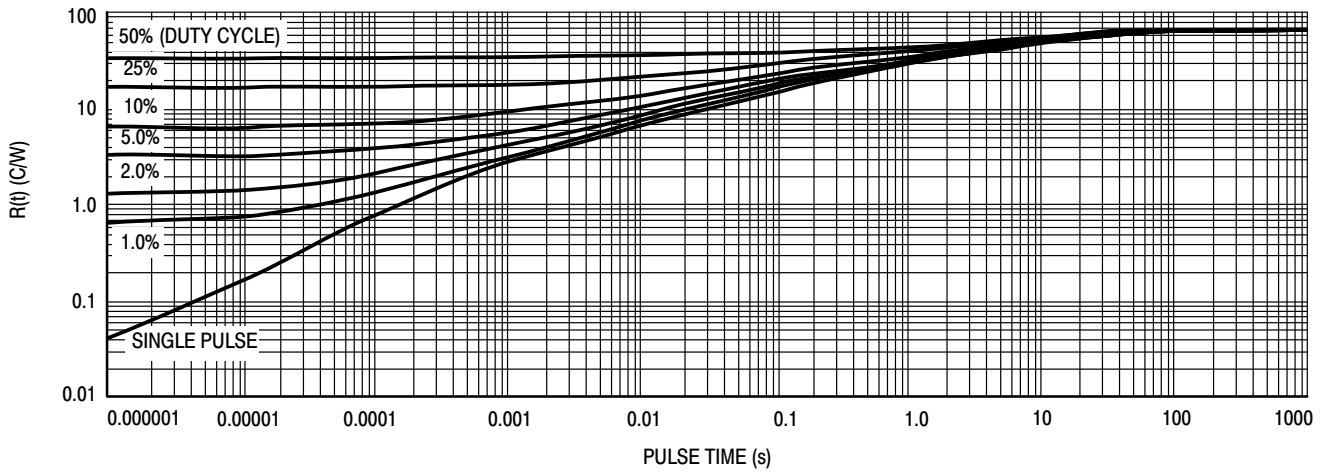
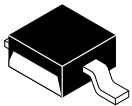


Figure 9. Thermal Response, Junction-to-Ambient (1 in^2 pad)

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 4:1

POWERMITE CASE 457 ISSUE G

DATE 12 JAN 2022

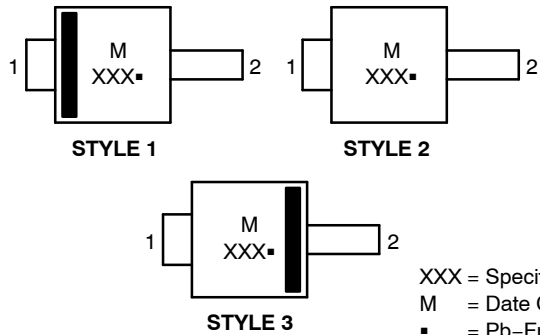


DIM	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	1.75	2.05	0.069	0.081
B	1.75	2.18	0.069	0.086
C	0.85	1.15	0.033	0.045
D	0.40	0.69	0.016	0.027
F	0.70	1.00	0.028	0.039
H	-0.05	0.10	-0.002	0.004
J	0.10	0.25	0.004	0.010
K	3.60	3.90	0.142	0.154
L	0.50	0.80	0.020	0.031
R	1.20	1.50	0.047	0.059
S	0.50 REF		0.019 REF	

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM THE TERMINAL TIP.

GENERIC MARKING DIAGRAMS*



- | | | |
|--|---|--|
| STYLE 1:
PIN 1. CATHODE
2. ANODE | STYLE 2:
PIN 1. ANODE OR CATHODE
2. CATHODE OR ANODE (BI-DIRECTIONAL) | STYLE 3:
PIN 1. ANODE
2. CATHODE |
|--|---|--|

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

XXX = Specific Device Code
M = Date Code
▪ = Pb-Free Package

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